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(54) Title: HIGH CLAMP FORCE ELECTROSTATIC CHUCK FOR NON-FLAT SUBSTRATES

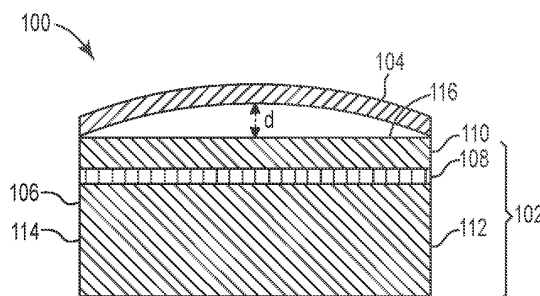


FIG. 1

(57) Abstract: An electrostatic chuck includes an electrode and a dielectric layer. When a voltage is applied to the electrode, the electrode is configured to generate an electrostatic force sufficient to flatten a non-flat substrate. The voltage applied to the electrode generates the electrostatic force sufficient to flatten the non-flat substrate such that a surface of the flattened substrate is substantially in contact with a surface of the electrostatic chuck.



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